

Product Change Notification / Cl	ENO-12HYA	S450	
Date:			
31-Jul-2023			
<b>Product Category:</b>			
Microprocessors			
PCN Type:			
Manufacturing Change			
Notification Subject:			
CCB 6009 Final Notice: Qualification device family available in 324L LFBGA		additional assembly site for selected ATSAMA5 nm) package.	D3xx
Affected CPNs:			
CENO-12HYAS450_Affected_CPN_0 CENO-12HYAS450_Affected_CPN_0			
Notification Text:			
PCN Status:Final Notification			
PCN Type:Manufacturing Change			
•		files found in the Affected CPNs section. entical files in two formats (.pdf and .xls)	
<b>Description of Change:</b> Qualification device family available in 324L LFBGA		additional assembly site for selected ATSAMA5 nm) package.	D3xx
Pre and Post Change Summary:			
Pre	e Change	Post Change	

	ATX	ATX Semiconductor	ASE Inc.		
Assembly Site	Semiconductor (Shanghai) Co. Ltd	(Shanghai) Co. Ltd	(ASEK)		
	(ASSH)	(ASSH)			
Wire Material	CuPd	CuPd	CuPdAu		
Die Attach Material	2100AS	2100AS	2100AC		
Molding Compound Material	KE-G1250LKDS	KE-G1250LKDS	KE-G1250NAS		
Substrate Core Material	CCL-HL832NX	CCL-HL832NX	CCL-HL832NX(A-HS)		

Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying ASEK as an additional assembly site.

**Change Implementation Status:**In Progress

Estimated First Ship Date: August 21, 2023 (date code: 2334)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

# Time Table Summary:

	December 2022				>	July 2023				August 2023					
Workweek	4 9	5 0	5 1	5 2	5 3		2 7	2 8	2 9	3	3	3 2	3	3 4	3 5
Initial PCN Issue Date				Х											
Qual Report Availability											Х				
Final PCN Issue Date											Х				
Estimated Implementation Date														Х	

Method to Identify Change: Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** December 19, 2022: Issued initial notification.

July 31, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 21, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

PCN\_CENO-12HYAS450\_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CENO-12HYAS450 - CCB 6009 Final Notice: Qualification of ASEK as an additional assembly site for selected ATSAMA5D3xx device family available in 324L LFBGA (15x15x1.4mm) package.

## Affected Catalog Part Numbers (CPN)

ATSAMA5D35A-CN

ATSAMA5D31A-CU

ATSAMA5D33A-CU

ATSAMA5D34A-CU

ATSAMA5D35A-CU

ATSAMA5D36A-CU

ATSAMA5D31A-CUC21

ATSAMA5D35A-CUC22

ATSAMA5D36A-CUC23

ATSAMA5D36A-CN

ATSAMA5D35A-CNR

ATSAMA5D36A-CNR

ATSAMA5D31A-CUR

ATSAMA5D33A-CUR

ATSAMA5D34A-CUR

ATSAMA5D35A-CUR

ATSAMA5D36A-CUR

ATSAMA5D31A-CURC21

ATSAMA5D35A-CURC22

ATSAMA5D36A-CURC23

Date: Monday, July 31, 2023